IEEE ISICAS 2025 Sponsorship Opportunities and Packages

IEEE ISICAS 2025's organizing committee has created a set of sponsorship opportunity packages to provide the best possible Return on Investment for your business: Gold, Platinum, and Diamond. For more information, please contact our Sponsorship/Exhibition Co-Chairs:

Xinsheng Wang, Harbin Institute of Technology, Weihai （xswang@hit.edu.cn）
Wenning Jiang. Fudan University （wenningjiang@fudan.edu.cn）
Yuan Du, Nanjing University （yuandu@nju.edu.cn）
Li Du, Nanjing University （ldu@nju.edu.cn）
Zhihong Luo, Primarius Technologies Co., Ltd. （zh.luo@primarius-tech.com ）

Option 1：Standard Packages

Sponsorship Packages	Exhibitor	Gold	Platinum	Diamond
Amount	$2K	$5K	$10K	$15K
Maximum available slots	30	12	5	3
Number of full registrations included	/	1	3	5
One exhibition booth	☑	☑	☑	☑
Listed as exhibitor/promotional sponsor on website & printed materials	☑	☑	☑	☑
Company logo on the final program	☑	☑	☑	☑
Company logo on the website	☑	☑	☑	☑
Company logo on the opening slide of the conference	☑	☑	☑	☑
Recognition as Sponsor of Technical Session		☑	☑	☑
Recognition as Exclusive Sponsor of workshops/seasonal schools/live demos			☑	☑
Speaking opportunity at special industry session			☑	☑
Recognition as Sponsor of welcome reception			☑	☑
Company logo on delegate bag				☑
One-minute company video before plenary				☑
Access to a meeting room (interviews, hospitality) - reservation needed				☑

Option 2：Itemized Sponsorship

- **Tea Break: $0.5K**
- **Lunch: $1K**
- **Travel Grant for students: 10 * $0.5K/Person**
- **Industrial Pre-doctoral Grant: 10 * $0.5K/Person**

About IEEE International Symposium on Integrated Circuits and Systems (ISICAS)

The Institute of Electrical and Electronics Engineers (IEEE) Circuits and System (CAS) Society is one of the largest society in IEEE with more than 20K members, including more than 8K student members. The Society has a strong global presence through 68 chapters, 59 joint chapters, and 124 student branch chapters. It supports a rich body of knowledge through 19 journals and fosters collaboration and innovation through 9 flagship and 34 co-sponsored conferences.

Among all, the IEEE International Symposium on Integrated Circuits and Systems (ISICAS) **is the top perimer flagship conference of the IEEE CAS Society.** ISICAS invites high-quality submissions presenting original work in the areas of integrated circuits and systems. Topics are in the areas of analog, digital, power, energy, biomedical, sensor interfaces, and communication systems.

The submissions must describe integrated circuit and system implementations with experimental results. All accepted papers will be published in special issues of our IEEE CAS flagship journals, such as **TCAS-I, TCAS-II, TVLSI, TBioCAS, TCASAI, and OJCAS**. Extended versions of recent conference papers already published with significant additional material are welcome.

IEEE International Symposium on Integrated Circuits and Systems (ISICAS) 2025

Qingdao, China
24 – 26 October 2025

The ISICAS 2025 will be held in Qingdao, Shandong, China from 24-26 October 2025.

- Theme: "Advances in Integrated Circuits and Systems: Bridging the Gap between Design and Implementation" – fully covers the field of interest of CAS Society.
- Experienced, regional balanced, and gender diverse team from academia and industry with strong support from government and local companies.
- There are about thousand people around the world will attend the conference, including students, professors, industry professionals, and government officials.
- The conference contains most areas of integrated circuits and systems. The topics include analog, digital, power, energy, biomedical, sensor interfaces, AI, and communication systems.

Past Conference:

2023 IEEE International Symposium on Integrated Circuits and Systems (ISICAS 2023) was held in Jeju, October 24-25 2023.

2024 IEEE International Symposium on Integrated Circuits and Systems (ISICAS 2024) was held in New Delhi, India from 18-19 October 2024.